

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE	
In re application of: <i>Evan G Colgan, et al.</i>	Date: <i>October 11, 2006</i>
Serial Number: <i>10/711,023</i>	Examiner: <i>Victor A Mandala</i>
	Confirmation No. <i>5022</i>
Filed: <i>August 18, 2004</i>	Group Art Unit: <i>2826</i>
Title: <i>MULTIPLE POWER DENSITY CHIP STRUCTURE</i>	IBM Corporation D/18G, B/300, Zip 482 2070 Route 52 Hopewell Junction, NY 12533-6531

AMENDMENT AFTER FINAL

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated August 11, 2006, the following
Amendment is being submitted to place the above identified application in prima
facie condition for allowance. Please amend the application as follows: